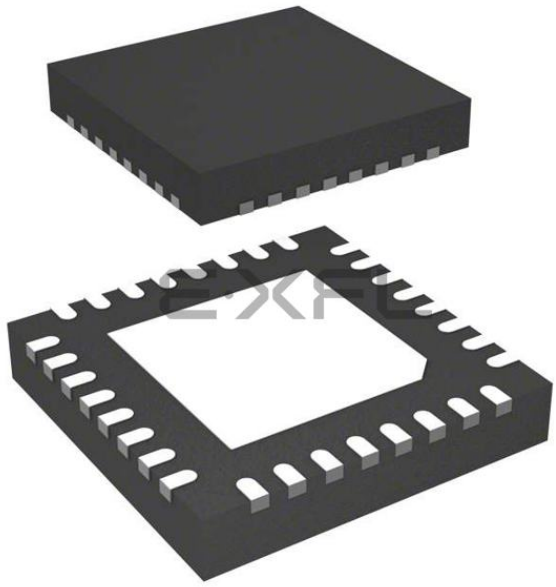

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	AVR
Core Size	8/16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	26
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 16x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atxmega32e5-m4u

1. Ordering Information

Ordering Code	Package[1][2][3]	Flash [Bytes]	EEPROM [Bytes]	SRAM [Bytes]	Speed [MHz]	Power supply [V]	Temp. [°C]
ATxmega8E5-AU	32A (7x7mm TQFP)	8K + 2K	512	1K	32	1.6 – 3.6	-40 – 85
ATxmega8E5-AUR[4]							
ATxmega8E5-MU	32Z (5x5mm VQFN)						
ATxmega8E5-MUR[4]							
ATxmega8E5-M4U	32MA (4x4mm UQFN)						
ATxmega8E5-M4UR[4]							
ATxmega16E5-AU	32A (7x7mm TQFP)	16K + 4K	512	2K	32	1.6 – 3.6	-40 – 85
ATxmega16E5-AUR[4]							
ATxmega16E5-MU	32Z (5x5mm VQFN)						
ATxmega16E5-MUR[4]							
ATxmega16E5-M4U	32MA (4x4mm UQFN)						
ATxmega16E5-M4UR[4]							
ATxmega32E5-AU	32A (7x7mm TQFP)	32K + 4K	1K	4K	32	1.6 – 3.6	-40 – 85
ATxmega32E5AUR[4]							
ATxmega32E5-MU	32Z (5x5mm VQFN)						
ATxmega32E5-MUR[4]							
ATxmega32E5-M4U	32MA (4x4mm UQFN)						
ATxmega32E5-M4UR[4]							
ATxmega8E5-AN	32A (7x7mm TQFP)	8K + 2K	512	1K	32	1.6 – 3.6	-40 – 105
ATxmega8E5-ANR[4]							
ATxmega8E5-MN	32Z (5x5mm VQFN)						
ATxmega8E5-MNR[4]							
ATxmega8E5-M4UN	32MA (4x4mm UQFN)						
ATxmega8E5-M4UNR[4]							
ATxmega16E5-AN	32A (7x7mm TQFP)	16K + 4K	512	2K	32	1.6 – 3.6	-40 – 105
ATxmega16E5-ANR[4]							
ATxmega16E5-MN	32Z (5x5mm VQFN)						
ATxmega16E5-MNR[4]							
ATxmega16E5-M4UN	32MA (4x4mm UQFN)						
ATxmega16E5-M4UNR[4]							

7. CPU

7.1 Features

- 8/16-bit, high-performance Atmel AVR RISC CPU
- 142 instructions
- Hardware multiplier
- 32x8-bit registers directly connected to the ALU
- Stack in RAM
- Stack pointer accessible in I/O memory space
- Direct addressing of up to 16MB of program memory and 16MB of data memory
- True 16/24-bit access to 16/24-bit I/O registers
- Efficient support for 8-, 16-, and 32-bit arithmetic
- Configuration change protection of system-critical features

7.2 Overview

All AVR XMEGA devices use the 8/16-bit AVR CPU. The main function of the CPU is to execute the code and perform all calculations. The CPU is able to access memories, perform calculations, control peripherals, and execute the program in the flash memory. Interrupt handling is described in a separate section, refer to “Interrupts and Programmable Multilevel Interrupt Controller” on page 28.

7.3 Architectural Overview

In order to maximize performance and parallelism, the AVR CPU uses a Harvard architecture with separate memories and buses for program and data. Instructions in the program memory are executed with single-level pipelining. While one instruction is being executed, the next instruction is pre-fetched from the program memory. This enables instructions to be executed on every clock cycle. For details of all AVR instructions, refer to http://www.atmel.com/avr.

8. Memories

8.1 Features

- Flash program memory
  - One linear address space
  - In-system programmable
  - Self-programming and boot loader support
  - Application section for application code
  - Application table section for application code or data storage
  - Boot section for application code or bootloader code
  - Separate read/write protection lock bits for all sections
  - Built in fast CRC check of a selectable flash program memory section
- Data memory
  - One linear address space
  - Single-cycle access from CPU
  - SRAM
  - EEPROM
    - Byte and page accessible
    - Memory mapped for direct load and store
  - I/O memory
    - Configuration and status registers for all peripherals and modules
    - Four bit-accessible general purpose registers for global variables or flags
  - Bus arbitration
    - Deterministic handling of priority between CPU, EDMA controller, and other bus masters
  - Separate buses for SRAM, EEPROM, and I/O memory
    - Simultaneous bus access for CPU and EDMA controller
- Production signature row memory for factory programmed data
  - ID for each microcontroller device type
  - Serial number for each device
  - Calibration bytes for factory calibrated peripherals
- User signature row
  - One flash page in size
  - Can be read and written from software
  - Content is kept after chip erase

8.2 Overview

The Atmel AVR architecture has two main memory spaces, the program memory and the data memory. Executable code can reside only in the program memory, while data can be stored in the program memory and the data memory. The data memory includes the internal SRAM, and EEPROM for nonvolatile data storage. All memory spaces are linear and require no memory bank switching. Nonvolatile memory (NVM) spaces can be locked for further write and read/write operations. This prevents unrestricted access to the application software.

A separate memory section contains the fuse bytes. These are used for configuring important system functions, and can only be written by an external programmer.

The available memory size configurations are shown in “Ordering Information” on page 2”. In addition, each device has a Flash memory signature row for calibration data, device identification, serial number etc.

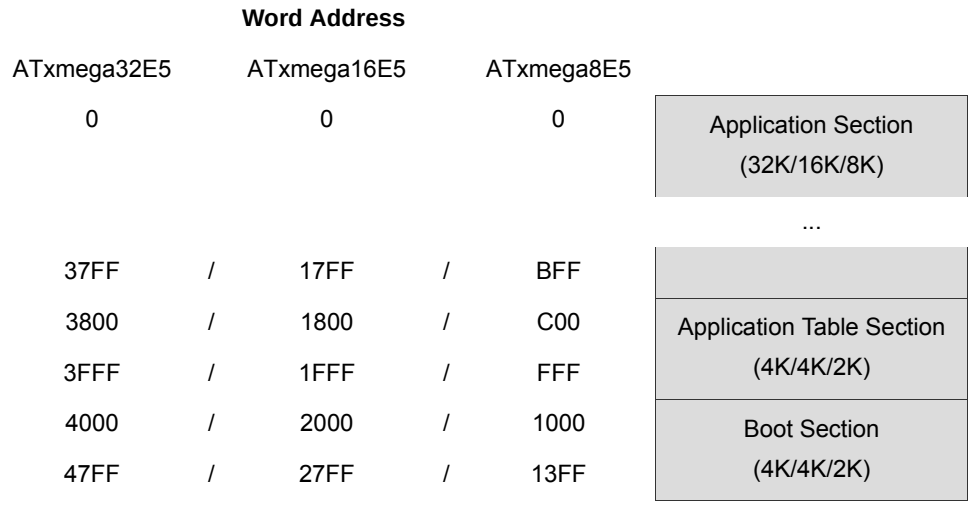
8.3 Flash Program Memory

The Atmel AVR XMEGA devices contain on-chip, in-system reprogrammable flash memory for program storage. The flash memory can be accessed for read and write from an external programmer through the PDI or from application software running in the device.

All AVR CPU instructions are 16 or 32 bits wide, and each flash location is 16 bits wide. The flash memory is organized in two main sections, the application section and the boot loader section. The sizes of the different sections are fixed, but device-dependent. These two sections have separate lock bits, and can have different levels of protection. The store program memory (SPM) instruction, which is used to write to the flash from the application software, will only operate when executed from the boot loader section.

The application section contains an application table section with separate lock settings. This enables safe storage of nonvolatile data in the program memory.

Figure 8-1. Flash Program Memory (hexadecimal address)



8.3.1 Application Section

The Application section is the section of the flash that is used for storing the executable application code. The protection level for the application section can be selected by the boot lock bits for this section. The application section can not store any boot loader code since the SPM instruction cannot be executed from the application section.

8.3.2 Application Table Section

The application table section is a part of the application section of the flash memory that can be used for storing data. The size is identical to the boot loader section. The protection level for the application table section can be selected by the boot lock bits for this section. The possibilities for different protection levels on the application section and the application table section enable safe parameter storage in the program memory. If this section is not used for data, application code can reside here.

8.3.3 Boot Loader Section

While the application section is used for storing the application code, the boot loader software must be located in the boot loader section because the SPM instruction can only initiate programming when executing from this section. When programming, the CPU is halted, waiting for the flash operation to complete. The SPM instruction can access the entire flash, including the boot loader section itself. The protection level for the boot loader section can be selected by the boot loader lock bits. If this section is not used for boot loader software, application code can be stored here.

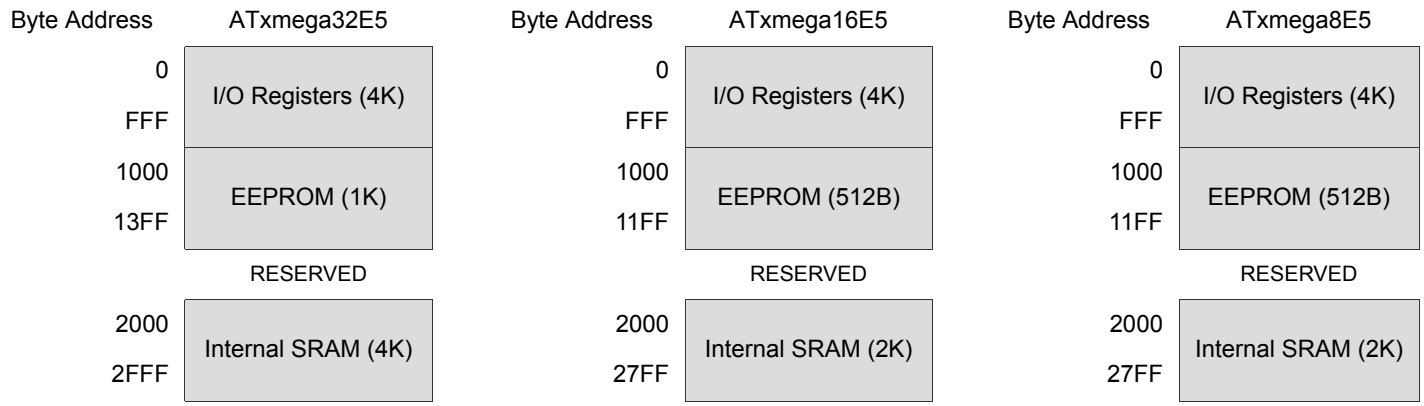
8.3.4 Production Signature Row

The production signature row is a separate memory section for factory programmed data. It contains calibration data for functions such as oscillators and analog modules. Some of the calibration values will be automatically loaded to the corresponding module or peripheral unit during reset. Other values must be loaded from the signature row and written to

8.5 Data Memory

The data memory contains the I/O memory, internal SRAM and EEPROM. The data memory is organized as one continuous memory section, see Table 8-2 on page 15. To simplify development, I/O Memory, EEPROM and SRAM will always have the same start addresses for all XMEGA devices.

Figure 8-2. Data Memory Map (hexadecimal value)



8.6 EEPROM

Atmel AVR XMEGA E5 devices have EEPROM for nonvolatile data storage. It is memory mapped and accessed in normal data space. The EEPROM supports both byte and page access. EEPROM allows highly efficient EEPROM reading and EEPROM buffer loading. When doing this, EEPROM is accessible using load and store instructions. EEPROM will always start at hexadecimal address 0x1000.

8.7 I/O Memory

The status and configuration registers for peripherals and modules, including the CPU, are addressable through I/O memory locations. All I/O locations can be accessed by the load (LD/LDS/LDD) and store (ST/STS/STD) instructions, which are used to transfer data between the 32 registers in the register file and the I/O memory. The IN and OUT instructions can address I/O memory locations in the range of 0x00 to 0x3F directly. In the address range 0x00 - 0x1F, single-cycle instructions for manipulation and checking of individual bits are available.

The I/O memory address for all peripherals and modules in XMEGA E5 is shown in the “Peripheral Module Address Map” on page 61.

8.7.1 General Purpose I/O Registers

The lowest four I/O memory addresses are reserved as general purpose I/O registers. These registers can be used for storing global variables and flags, as they are directly bit-accessible using the SBI, CBI, SBIS, and SBIC instructions.

8.8 Data Memory and Bus Arbitration

Since the data memory is organized as three separate sets of memories, the different bus masters (CPU, EDMA controller read and EDMA controller write, etc.) can access different memory sections at the same time.

8.9 Memory Timing

Read and write access to the I/O memory takes one CPU clock cycle. A write to SRAM takes one cycle, and a read from SRAM takes two cycles. For burst read (EDMA), new data are available every cycle. EEPROM page load (write) takes one cycle, and three cycles are required for read. For burst read, new data are available every second cycle. Refer to the instruction summary for more details on instructions and instruction timing.

12. Power Management and Sleep Modes

12.1 Features

- Power management for adjusting power consumption and functions
- Five sleep modes
  - Idle
  - Power down
  - Power save
  - Standby
  - Extended standby
- Power reduction register to disable clock and turn off unused peripherals in active and idle modes

12.2 Overview

Various sleep modes and clock gating are provided in order to tailor power consumption to application requirements. This enables the Atmel AVR XMEGA microcontroller to stop unused modules to save power.

All sleep modes are available and can be entered from active mode. In active mode, the CPU is executing application code. When the device enters sleep mode, program execution is stopped and interrupts or a reset is used to wake the device again. The application code decides which sleep mode to enter and when. Interrupts from enabled peripherals and all enabled reset sources can restore the microcontroller from sleep to active mode.

In addition, power reduction registers provide a method to stop the clock to individual peripherals from software. When this is done, the current state of the peripheral is frozen, and there is no power consumption from that peripheral. This reduces the power consumption in active mode and idle sleep modes and enables much more fine-tuned power management than sleep modes alone.

12.3 Sleep Modes

Sleep modes are used to shut down modules and clock domains in the microcontroller in order to save power. XMEGA microcontrollers have five different sleep modes tuned to match the typical functional stages during application execution. A dedicated sleep instruction (SLEEP) is available to enter sleep mode. Interrupts are used to wake the device from sleep, and the available interrupt wake-up sources are dependent on the configured sleep mode. When an enabled interrupt occurs, the device will wake up and execute the interrupt service routine before continuing normal program execution from the first instruction after the SLEEP instruction. If other, higher priority interrupts are pending when the wake-up occurs, their interrupt service routines will be executed according to their priority before the interrupt service routine for the wake-up interrupt is executed. After wake-up, the CPU is halted for four cycles before execution starts.

The content of the register file, SRAM and registers are kept during sleep. If a reset occurs during sleep, the device will reset, start up, and execute from the reset vector.

12.3.1 Idle Mode

In idle mode the CPU and nonvolatile memory are stopped (note that any ongoing programming will be completed), but all peripherals, including the interrupt controller, event system and EDMA controller are kept running. Any enabled interrupt will wake the device.

12.3.2 Power-down Mode

In power-down mode, all clocks, including the real-time counter clock source, are stopped. This allows operation only of asynchronous modules that do not require a running clock. The only interrupts that can wake up the MCU are the two-wire interface address match interrupt and asynchronous port interrupts.

12.3.3 Power-save Mode

Power-save mode is identical to power down, with one exception. If the real-time counter (RTC) is enabled, it will keep running during sleep, and the device can also wake up from either an RTC overflow or compare match interrupt. Low power mode option of 8MHz internal oscillator enables instant oscillator wake-up time. This reduces the MCU wake-up time or enables the MCU wake-up from UART bus.

12.3.4 Standby Mode

Standby mode is identical to power down, with the exception that the enabled system clock sources are kept running while the CPU, peripheral, and RTC clocks are stopped. This reduces the wake-up time. The low power option of 8MHz internal oscillator can be enabled to further reduce the power consumption.

12.3.5 Extended Standby Mode

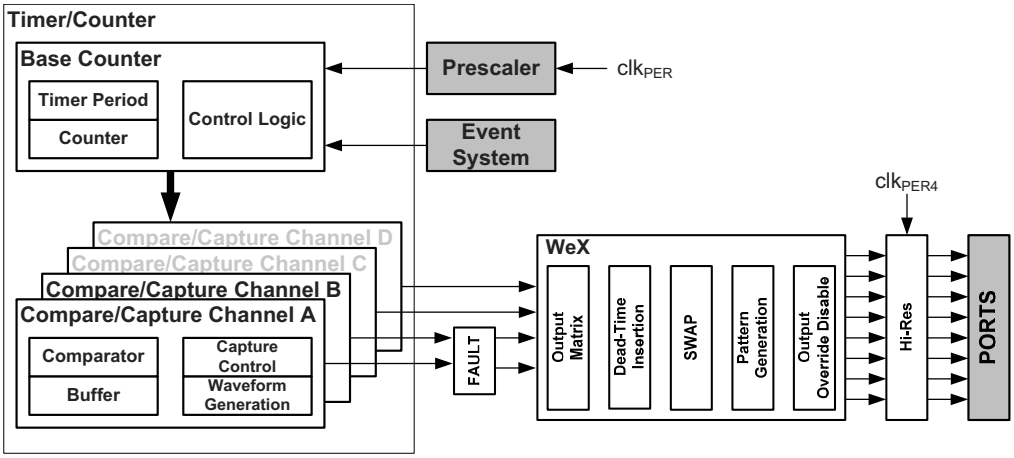
Extended standby mode is identical to power-save mode, with the exception that the enabled system clock sources are kept running while the CPU and peripheral clocks are stopped. This reduces the wake-up time. The low power option of 8MHz internal oscillator can be enabled to further reduce the power consumption.

There are two differences between timer/counter type 4 and type 5. Timer/counter 4 has four CC channels, and timer/counter 5 has two CC channels. Both timer/counter 4 and 5 can be set in 8-bit mode, allowing the application to double the number of compare and capture channels that then get 8-bit resolution.

Some timer/counters have extensions that enable more specialized waveform generation. The waveform extension (WeX) is intended for motor control, ballast, LED, H-bridge, power converters, and other types of power control applications. It enables more customized waveform output distribution, and low- and high-side channel output with optional dead-time insertion. It can also generate a synchronized bit pattern across the port pins. The high-resolution (hi-res) extension can increase the waveform resolution by four or eight times by using an internal clock source four times faster than the peripheral clock. The fault extension (FAULT) enables fault protection for safe and deterministic handling, disabling and/or shut down of external drivers.

A block diagram of the 16-bit timer/counter with extensions and closely related peripheral modules (in grey) is shown in Figure 17-1.

Figure 17-1. 16-bit Timer/counter and Closely Related Peripherals



PORTC has one timer/counter 4 and one timer/counter 5. PORTD has one timer/counter 5. Notation of these are TCC4 (timer/counter C4), TCC5, and TCD5, respectively.

18. WeX – Waveform Extension

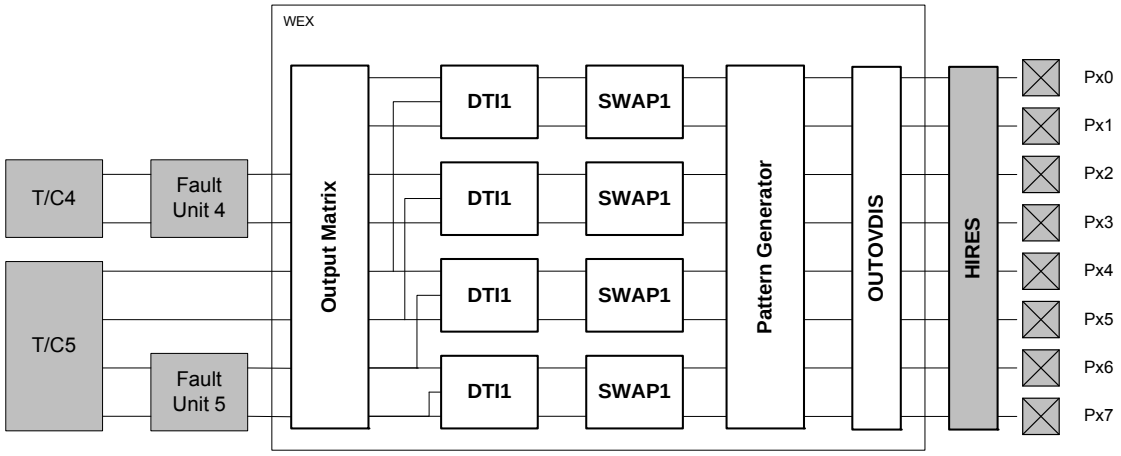
18.1 Features

- Module for more customized and advanced waveform generation
  - Optimized for various type of motor, ballast, and power stage control
- Output matrix for timer/counter waveform output distribution
  - Configurable distribution of compare channel output across port pins
  - Redistribution of dead-time insertion resource between TC4 and TC5
- Four dead-time insertion (DTI) units, each with
  - Complementary high and low side with non overlapping outputs
  - Separate dead-time setting for high and low side
  - 8-bit resolution
- Four swap (SWAP) units
  - Separate port pair or low high side drivers swap
  - Double buffered swap feature
- Pattern generation creating synchronized bit pattern across the port pins
  - Double buffered pattern generation

18.2 Overview

The waveform extension (WEX) provides extra functions to the timer/counter in waveform generation (WG) modes. It is primarily intended for motor control, ballast, LED, H-bridge, power converters, and other types of power control applications. The WEX consist of five independent and successive units, as shown in Figure 18-1.

Figure 18-1. Waveform Extension and Closely Related Peripherals



The output matrix (OTMX) can distribute and route out the waveform outputs from timer/counter 4 and 5 across the port pins in different configurations, each optimized for different application types. The dead time insertion (DTI) unit splits the four lower OTMX outputs into a two non-overlapping signals, the non-inverted low side (LS) and inverted high side (HS) of the waveform output with optional dead-time insertion between LS and HS switching.

The swap (SWAP) unit can swap the LS and HS pin position. This can be used for fast decay motor control. The pattern generation unit generates synchronized output waveform with constant logic level. This can be used for easy stepper motor and full bridge control.

21. RTC – 16-bit Real-Time Counter

21.1 Features

- 16-bit resolution
- Selectable clock source
  - 32.768kHz external crystal
  - External clock
  - 32.768kHz internal oscillator
  - 32kHz internal ULP oscillator
- Programmable 10-bit clock prescaling
- One compare register
- One period register
- Clear counter on period overflow
- Optional interrupt/event on overflow and compare match
- Correction for external crystal oscillator frequency error down to ±0.5ppm accuracy

21.2 Overview

The 16-bit real-time counter (RTC) is a counter that typically runs continuously, including in low power sleep modes, to keep track of time. It can wake up the device from sleep modes and/or interrupt the device at regular intervals.

The reference clock is typically the 1.024kHz output from a high-accuracy crystal of 32.768kHz, and this is the configuration most optimized for low power consumption. The faster 32.768kHz output can be selected if the RTC needs a resolution higher than 1ms. The RTC can also be clocked from an external clock signal, the 32.768kHz internal oscillator or the 32kHz internal ULP oscillator.

The RTC includes a 10-bit programmable prescaler that can scale down the reference clock before it reaches the counter. A wide range of resolutions and time-out periods can be configured. With a 32.768kHz clock source, the maximum resolution is 30.5µs, and time-out periods can range up to 2000 seconds. With a resolution of 1s, the maximum timeout period is more than 18 hours (65536 seconds). The RTC can give a compare interrupt and/or event when the counter equals the compare register value, and an overflow interrupt and/or event when it equals the period register value.

22. TWI – Two-Wire Interface

22.1 Features

- One two-wire interface
  - Phillips I^2C compatible
  - System Management Bus (SMBus) compatible
- Bus master and slave operation supported
  - Slave operation
  - Single bus master operation
  - Bus master in multi-master bus environment
  - Multi-master arbitration
  - Bridge mode with independent and simultaneous master and slave operation
- Flexible slave address match functions
  - 7-bit and general call address recognition in hardware
  - 10-bit addressing supported
  - Address mask register for dual address match or address range masking
  - Optional software address recognition for unlimited number of addresses
- Slave can operate in all sleep modes, including power-down
- Slave address match can wake device from all sleep modes
- 100kHz, 400kHz, and 1MHz bus frequency support
- Slew-rate limited output drivers
- Input filter for bus noise and spike suppression
- Support arbitration between start/repeated start and data bit (SMBus)
- Slave arbitration allows support for address resolve protocol (ARP) (SMBus)
- Supports SMBUS Layer 1 timeouts
- Configurable timeout values
- Independent timeout counters in master and slave (Bridge mode support)

22.2 Overview

The two-wire interface (TWI) is a bidirectional, two-wire communication interface. It is I^2C and System Management Bus (SMBus) compatible. The only external hardware needed to implement the bus is one pull-up resistor on each bus line.

A device connected to the bus must act as a master or a slave. One bus can have many slaves and one or several masters that can take control of the bus.

The TWI module supports master and slave functionality. The master and slave functionality are separated from each other, and can be enabled and operate simultaneously and separately. The master module supports multi-master bus operation and arbitration. It contains the baud rate generator. Quick command and smart mode can be enabled to auto-trigger operations and reduce software complexity. The master can support 100kHz, 400kHz, and 1MHz bus frequency.

The slave module implements 7-bit address match and general address call recognition in hardware. 10-bit addressing is also supported. A dedicated address mask register can act as a second address match register or as a register for address range masking. The slave continues to operate in all sleep modes, including power-down mode. This enables the slave to wake up the device from all sleep modes on TWI address match. It is possible to disable the address matching to let this be handled in software instead. By using the bridge option, the slave can be mapped to different pin locations. The master and slave can support 100kHz, 400kHz, and 1MHz bus frequency.

The TWI module will detect START and STOP conditions, bus collisions, and bus errors. Arbitration lost, errors, collision, and clock hold on the bus are also detected and indicated in separate status flags available in both master and slave modes.

Table 32-4. PORT R – Alternate Functions

PORT R	Pin #	XTAL	TOSC	EXTCLK	CLOCKOUT	EVENTOUT	RTCOUT	AC OUT
PR0	20	XTAL2	TOSC2		CLKOUT	EVOUT	RTCOUT	AC1 OUT
PR1	19	XTAL1	TOSC1	EXTCLK				AC0 OUT

Table 32-5. PORT D – Alternate Functions

PORT D	Pin #	ADCAPOS GAINPOS	TCD5	USART D0	TWID (Bridge)	XCL (LUT)	XCL (TC)	CLOCK OUT	EVENT OUT	RTCOUT	ACOUT	REFD
PD0	28	ADC8			SDA	IN1/ OUT0						AREF
PD1	27	ADC9		XCK0	SCL	IN2						
PD2	26	ADC10		RXD0		IN0	OC0					
PD3	25	ADC11		TXD0		IN3	OC1					
PD4	24	ADC12	OC5A			IN1/ OUT0		CLKOUT	EVOUT			
PD5	23	ADC13	OC5B	XCK0		IN2						
PD6	22	ADC14		RXD0		IN0				RTCOUT	AC1OUT	
PD7	21	ADC15		TXD0		IN3		CLKOUT	EVOUT		AC0OUT	

Figure 37-11.Idle Mode Supply Current vs. V_{CC}

f_{SYS} = 32.768kHz internal oscillator

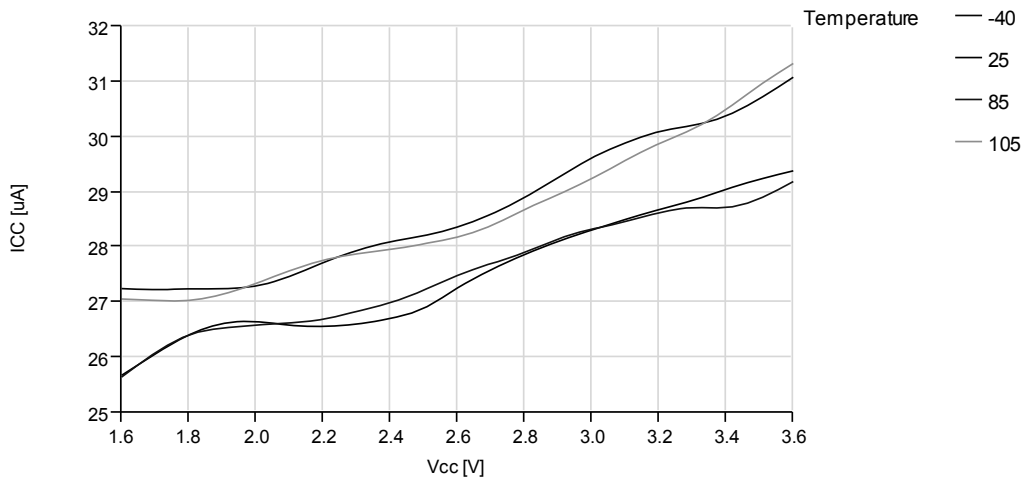


Figure 37-12.Idle Mode Supply Current vs. V_{CC}

f_{SYS} = 1MHz external clock

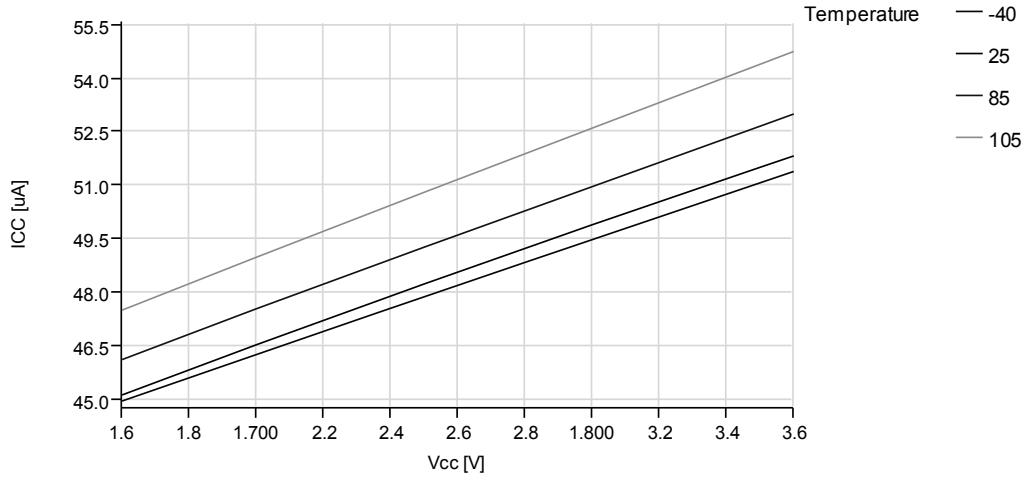
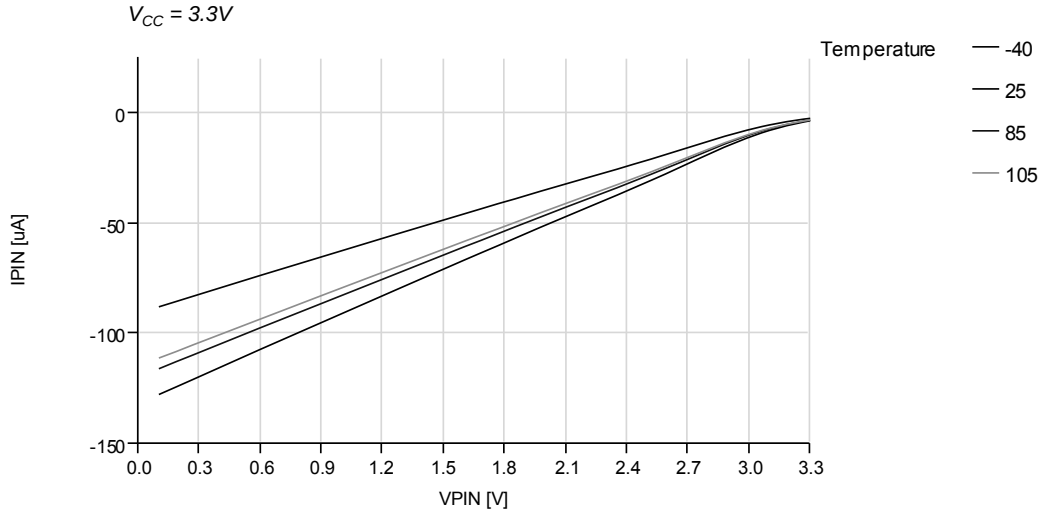


Figure 37-25.I/O Pin Pull-up Resistor Current vs. Input Voltage



37.2.2 Output Voltage vs. Sink/Source Current

Figure 37-26.I/O Pin Output Voltage vs. Source Current

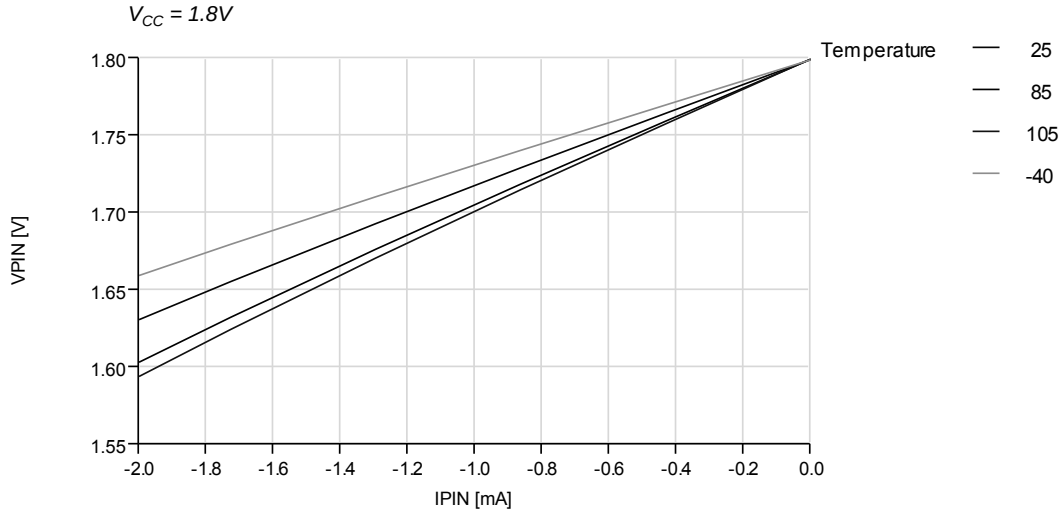


Figure 37-27.I/O Pin Output Voltage vs. Source Current

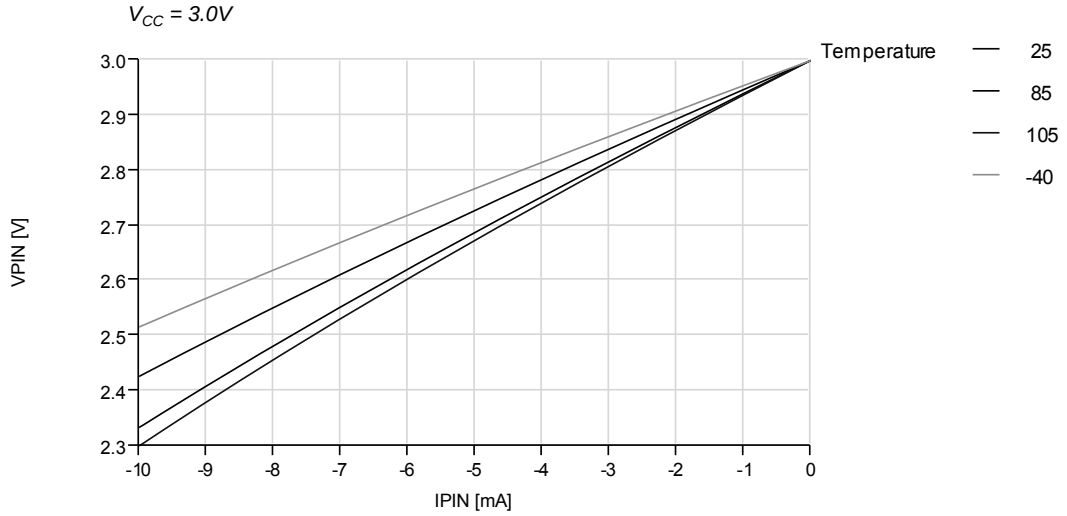


Figure 37-28.I/O Pin Output Voltage vs. Source Current

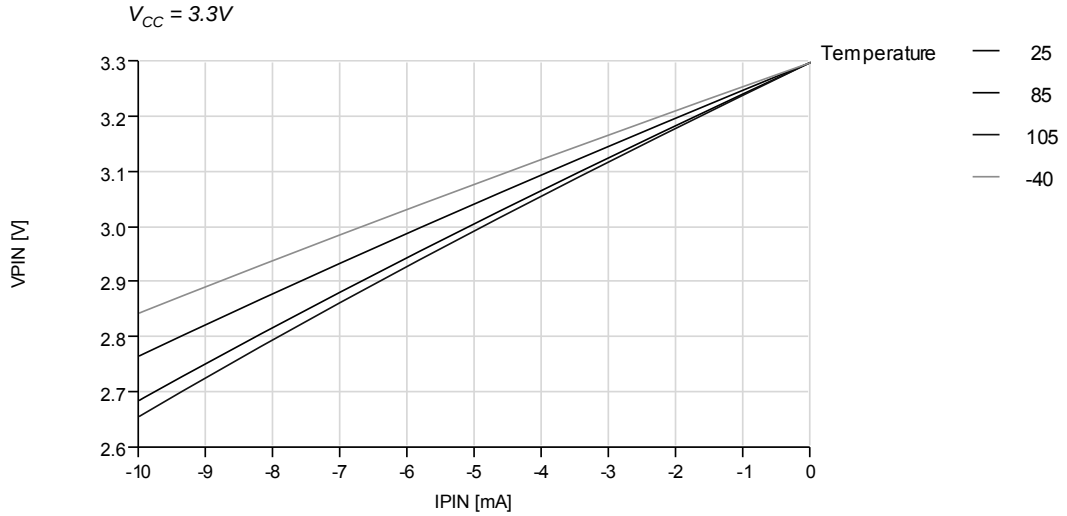


Figure 37-35.I/O Pin Input Threshold Voltage vs. V_{CC}

V_{IH} I/O pin read as "1"

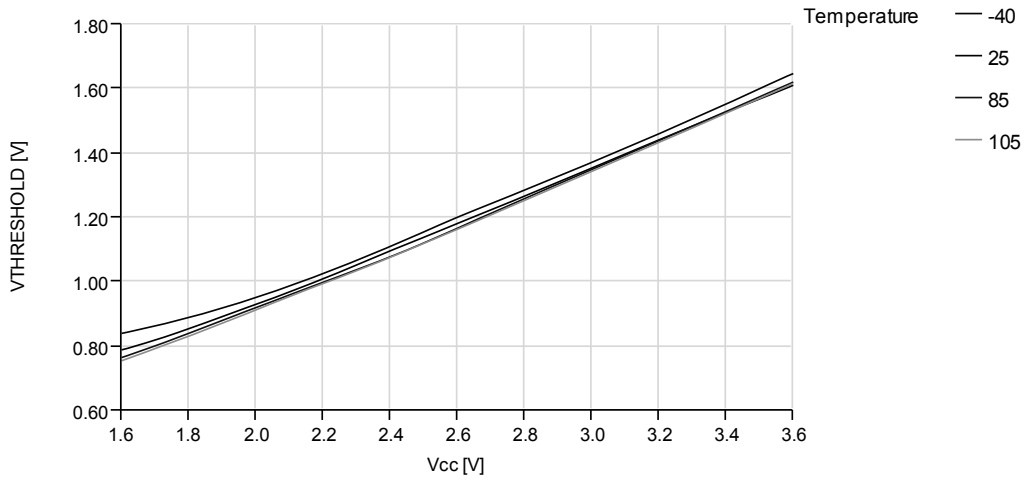


Figure 37-36.I/O Pin Input Threshold Voltage vs. V_{CC}

V_{IL} I/O pin read as "0"

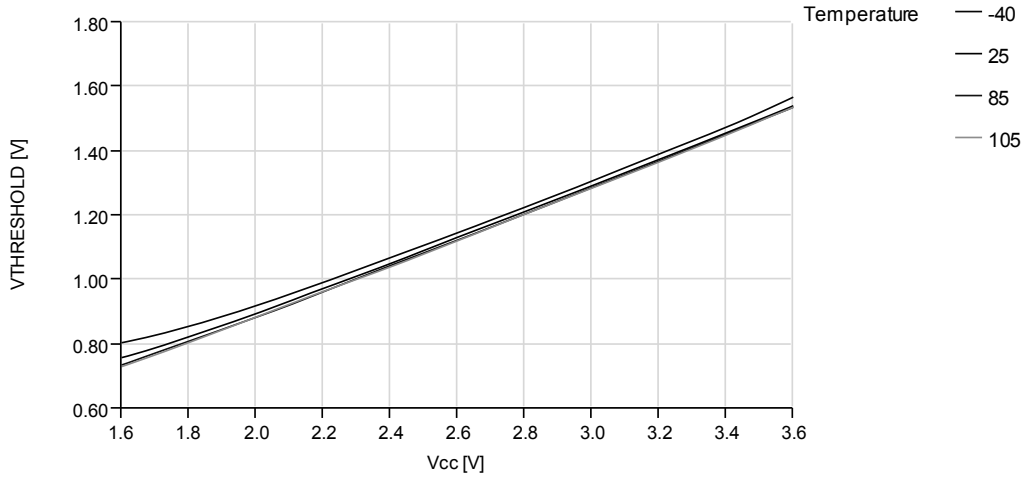


Figure 37-55.Analog Comparator Voltage Scaler vs. SCALEFAC

T = 25°C, V_{CC} = 3.0V

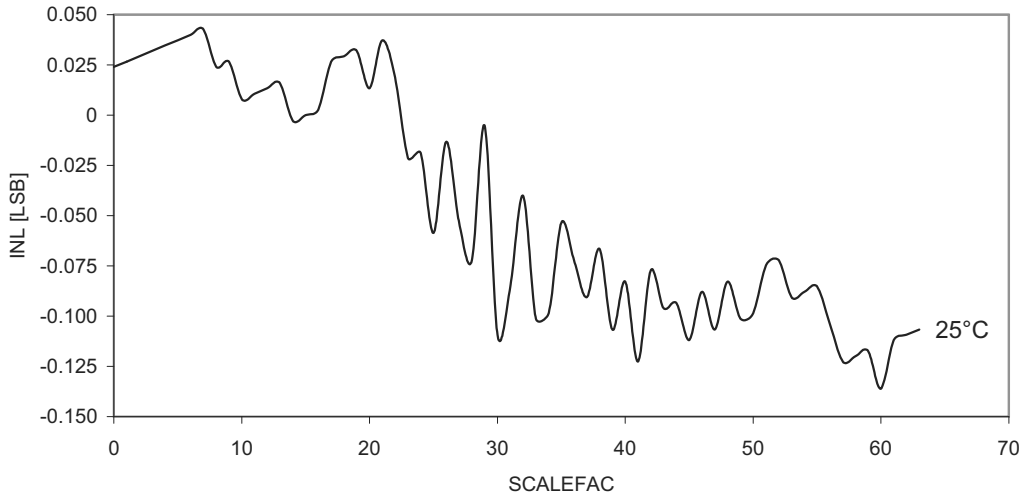


Figure 37-56.Analog Comparator Offset Voltage vs. Common Mode Voltage

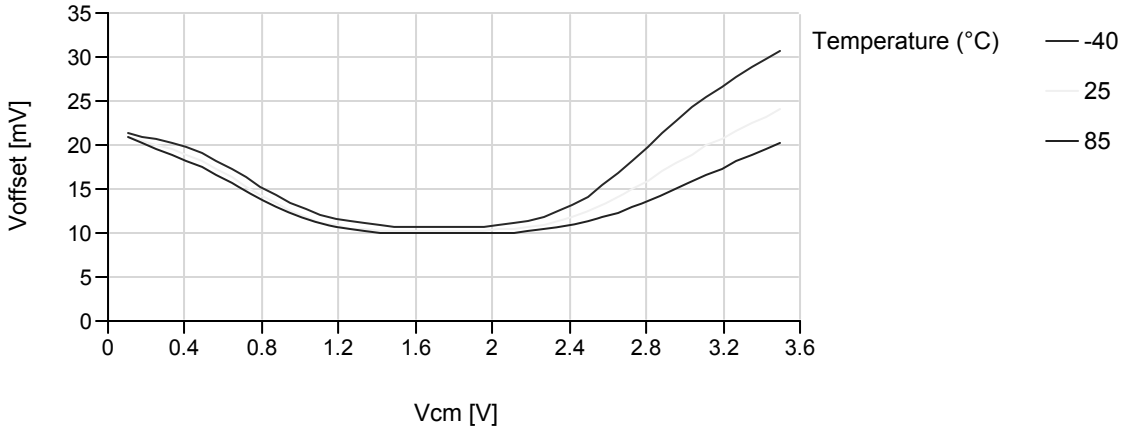


Figure 37-69.Power-on Reset Current Consumption vs. V_{CC}

BOD level = 3.0V, enabled in sampled mode

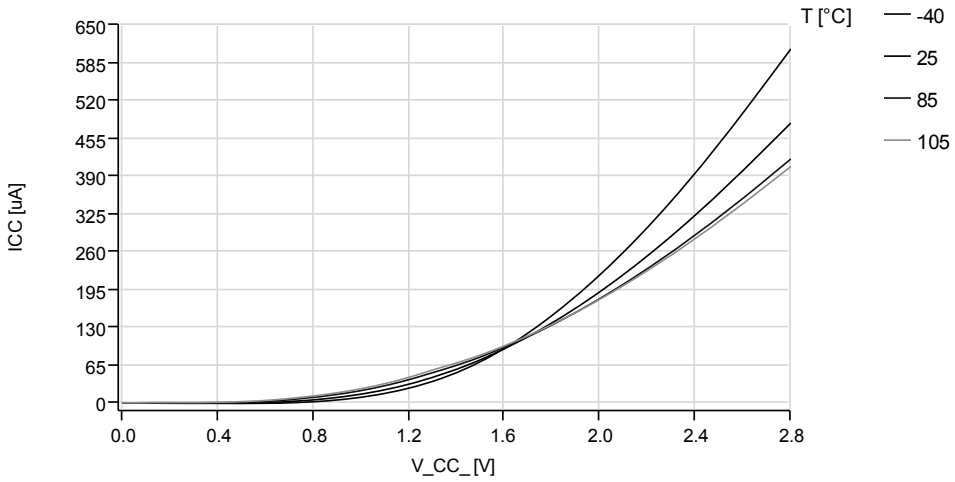
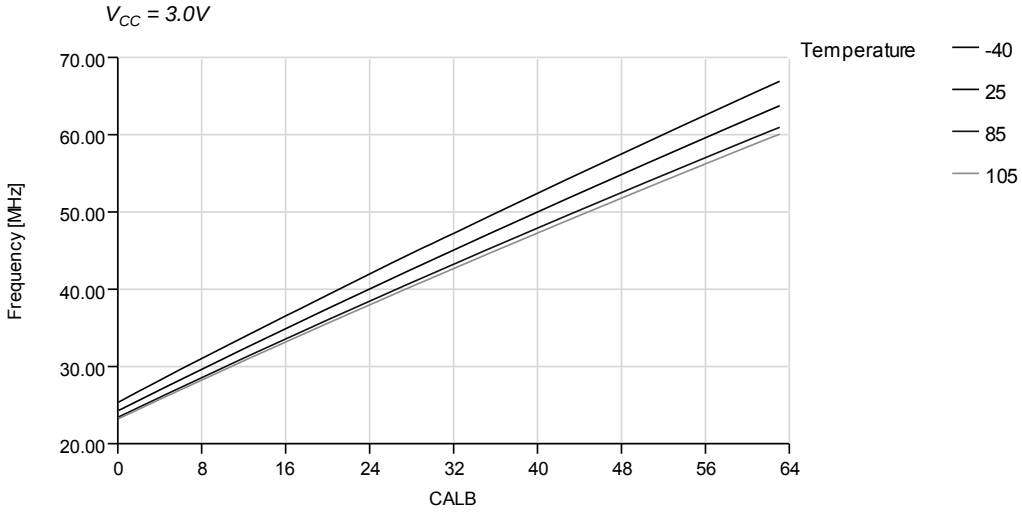
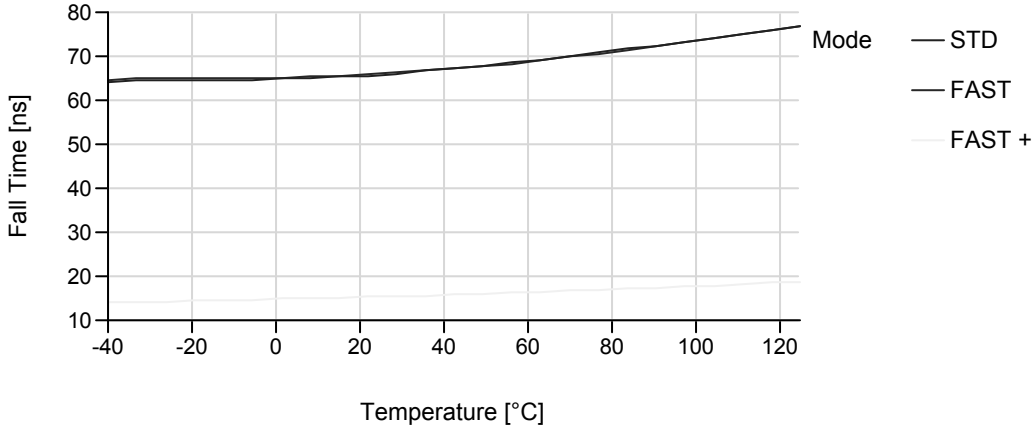


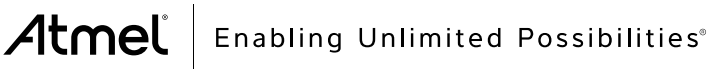
Figure 37-82. 32MHz internal Oscillator Frequency vs. CALB Calibration Value



37.11 Two-wire Interface Characteristics

Figure 37-83. SDA Fall Time vs. Temperature





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